



群創光電2024年下半年法人說明會

2024年8月5日

免責聲明

群創光電股份有限公司對於現狀期待與預測的陳述是前瞻性的陳述，實際的結果可能因為已知或未知之風險、不確定性及其他之因素，而與前瞻性陳述所包含或暗示的內容有明顯出入。這些前瞻性陳述並不是群創光電對未來履行的保證，因此您不應依賴此前瞻性陳述。除非法律有所要求，否則群創光電不負責更新、更正任何前瞻性陳述，不論日後有發生新資訊、事件等。

會議議程



1. 面板市場概況
2. 公司營運與策略
3. 財務報表摘要
4. Q&A

短期-按需生產策略有利市場穩定

- 面板價格隨零組件及市場需求波動
- 庫存維持在低/健康水位
- 成本控管為首要任務

不確定性：

1. 供應鏈不確定性(ex. 缺料、物流變數)
2. 地緣政治
3. 生產不確定性 (ex. 地震)



- 低庫存健康水位助益客戶新產品開案
- 各產品平均尺寸均見增長
- 產品應用多樣化

- 未來兩年無新增電視產能
- 產品平均尺寸增長加速產能去化
- 舊世代產線淘汰有助保持緊平衡的供需狀態

TV



成長動能:

- ✓ 尺寸增長：全球電視面板出貨平均尺寸年對年成長1.4”(51.8”in Y2024(F))

更新:

1. 維持緊平衡供需趨勢

IT



成長動能:

- ✓ NB&MNT平均尺寸增長
- ✓ Win10系統汰換潮
- ✓ AI PC 換機潮

更新:

1. Win10系統汰換潮及AI PC換機潮
2. MiniLED / MicroLED 作為高階產品選項; 入門機種可沿用LCD

Automotive



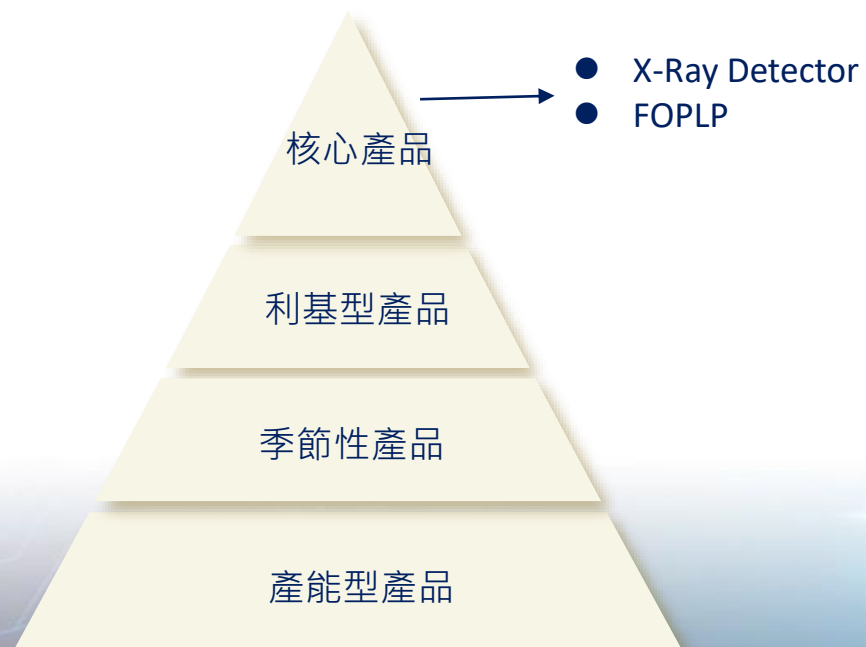
成長動能:

- ✓ 平均出貨尺寸增長
- ✓ 電動車促銷

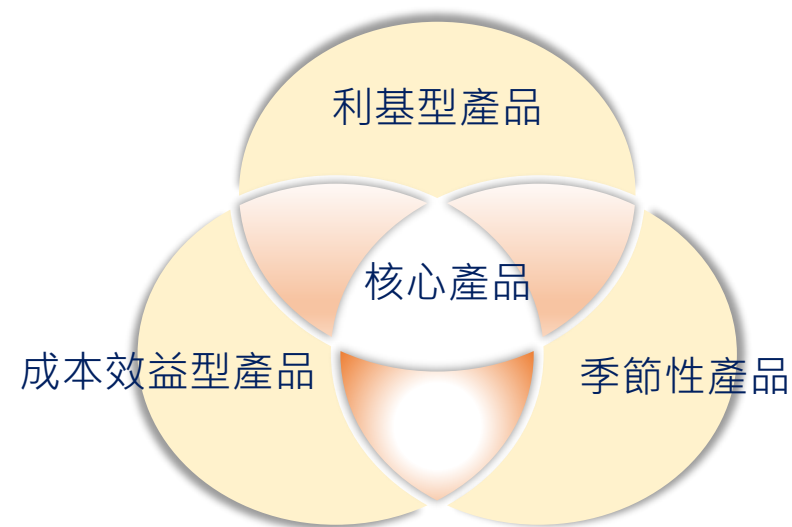
更新:

1. 儘管新車銷量緩降，車用面板平均尺寸增長與電動車的促銷帶動出貨
2. MiniLED / MicroLED 作為高階產品選項; 入門款式可沿用LCD

產能調控



價值創造

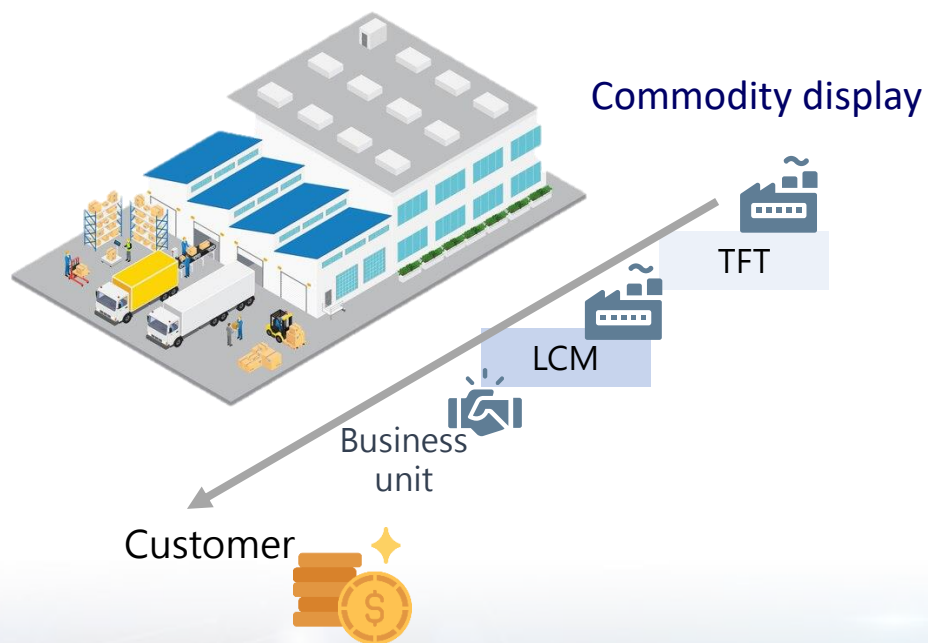


群創定位

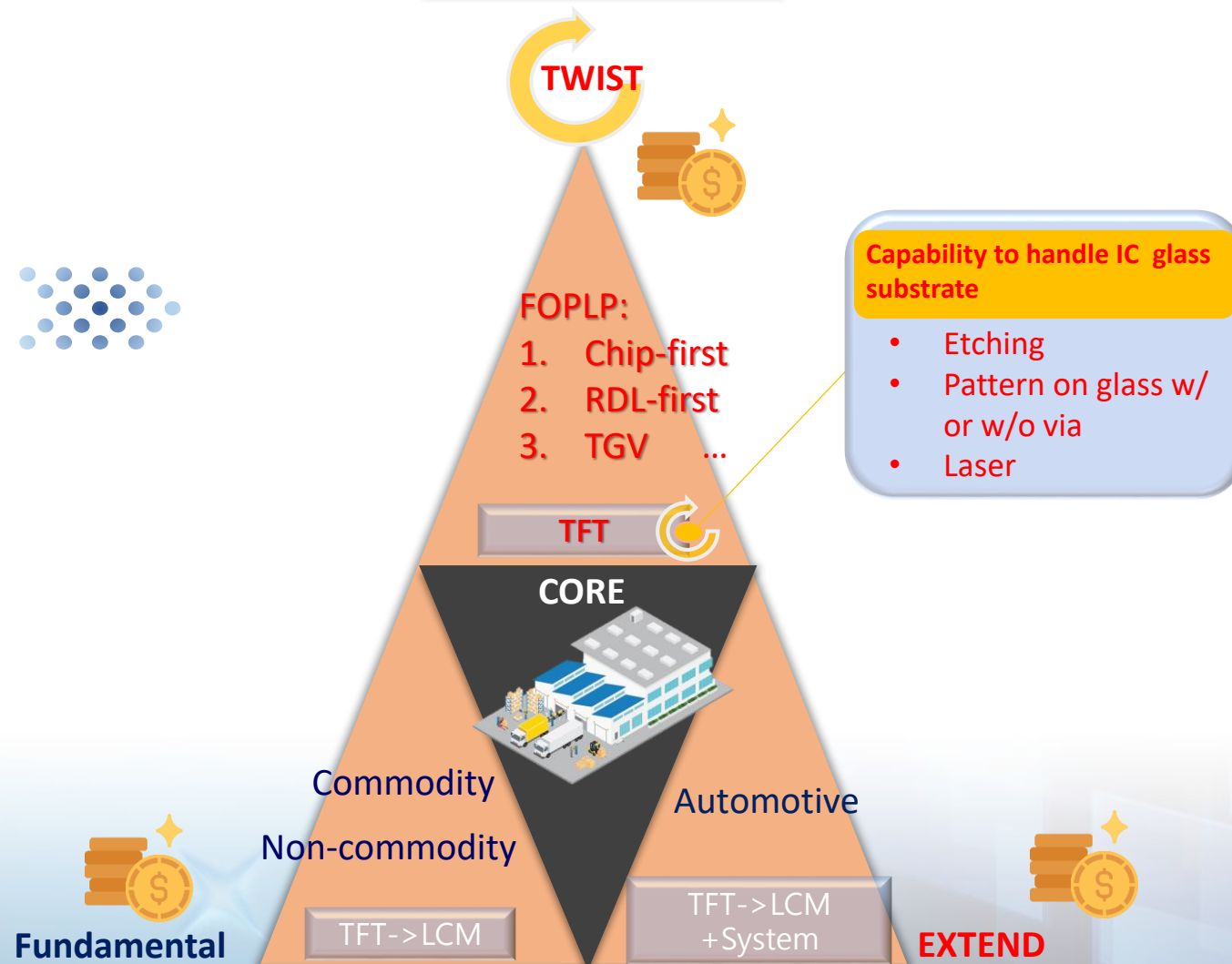
- 提供多元化技術及規格的面板
- IC 玻璃基板處理

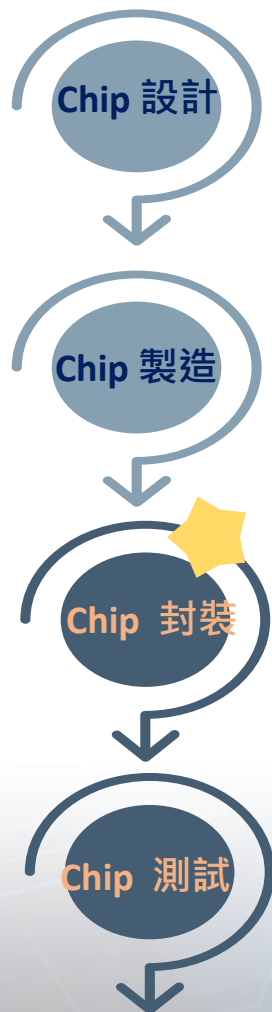
直線式

- 傳統商業模式

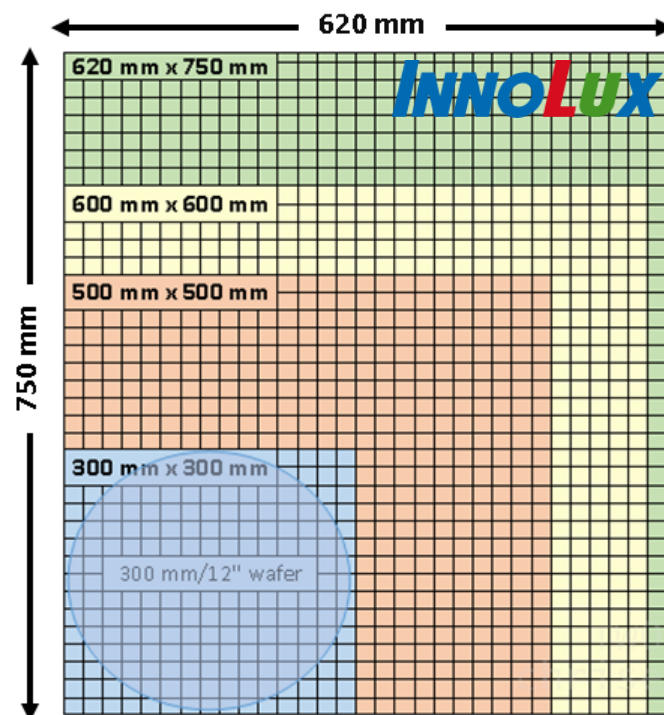


多角化



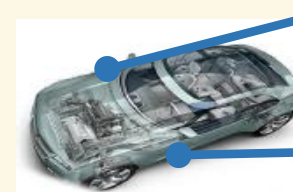


Innolux FOPLP
6.X 倍的生產面積



Chip-First

- ✓ Low contact resistance, high breakdown voltage, high reliability performance
- ✓ IC package in Automotive for short/mid term goal

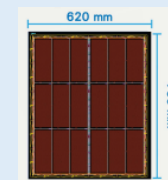


Ex. **77GHz** Radar transceiver
Chip-First for High Frequency

Ex. **650V** DC/DC convertor
Chip-First for High Power

RDL-First

- ✓ Innolux RDL fan-out substrate provide cost competitive solution for AI and HPC chip-let application with fine pitch pattern.
- ✓ Strip (95x240mm) or sub-panel (297x240) format delivery.

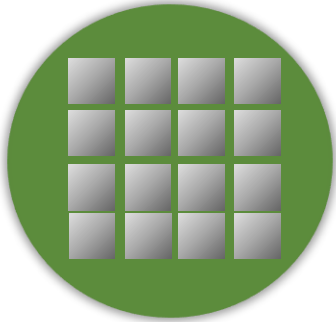


TGV

- ✓ TGV (Through-glass-via) process on glass substrate
- ✓ Target high speed for generative AI/ HPC application
- ✓ Substrate format delivery



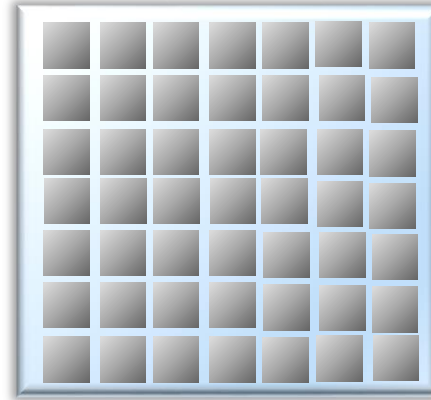
Silicon wafer based substrate



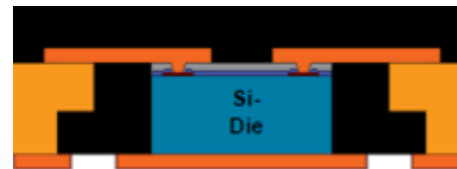
Wire bond at lead frame or substrate



Panel based glass substrate



Copper direct interconnect with EMC 6 sides encapsulation



Panel vs. wafer

- ✓ Better area utilization
- ✓ Better productivity and material usage efficiency

Panel glass vs. silicon

- ✓ Better cost competitiveness in glass with stronger bargaining power (INX as panel maker)
- ✓ Larger size possibility
- ✓ Heterogeneous package

Wire bond vs. copper direct interconnect

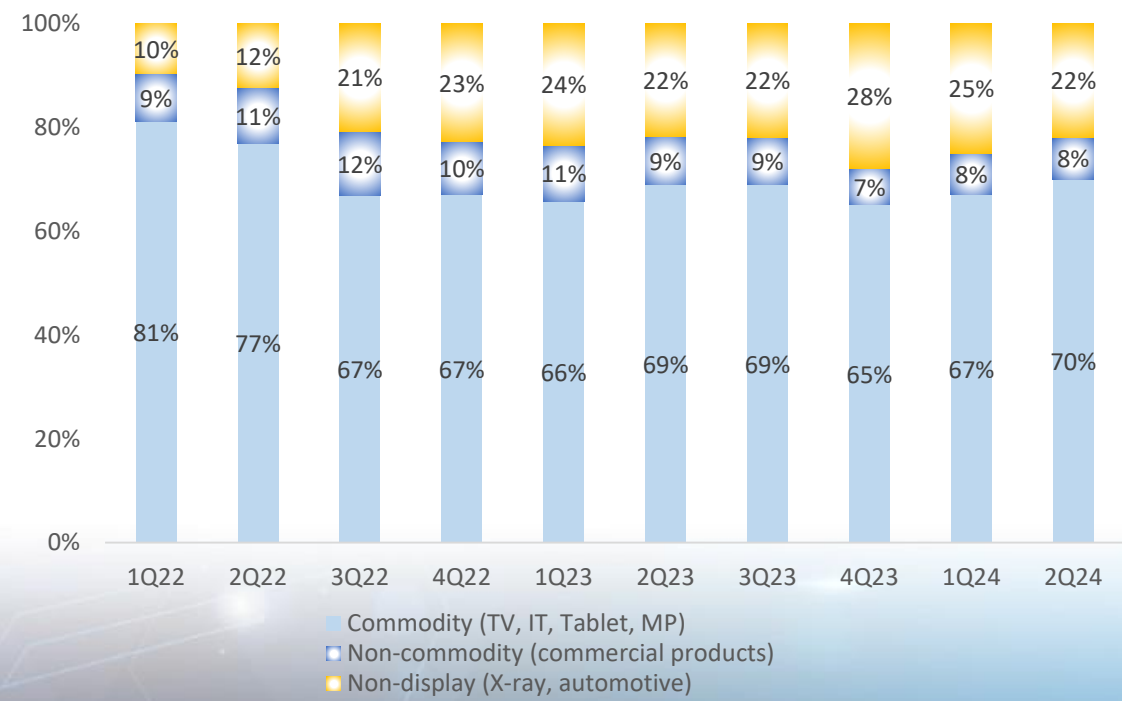
- ✓ Shorter trace means lower resistance and lower signal interference
- ✓ Interconnection provide package miniaturization

EMC 6 sides encapsulation

- ✓ MSL-1 (highest level of moisture proof)
- ✓ Better heat dissipation
- ✓ High electrical current 100A and high voltage of 650V.

- 各產品領域群季營收均呈現成長
- 不同產品別毛利率呈差異化

領域群營收



領域群營收及平均毛利率

Product Type	Revenue (NT\$ million)			Average GM
	2Q24	QoQ (%)	% share	1H24
Non-display	12,734	1%	22%	11-15%
Non-commodity	4,601	12%	8%	21-25%
Commodity	39,526	17%	70%	6-10%

合併綜合損益表摘要

新台幣百萬元 (除每股盈餘為元)	2024 年第二季		2024 年第一季		季成長 %	2023 年第二季	
營業收入淨額	56,861	100.0%	50,492	100.0%	12.6%	55,087	100.0%
營業成本	51,150	90.0%	48,351	95.8%	5.8%	54,735	99.4%
營業毛利	5,711	10.0%	2,141	4.2%	166.7%	353	0.6%
營業費用	5,347	9.4%	5,312	10.5%	0.6%	5,692	10.3%
營業淨利(損)	364	0.6%	(3,171)	-6.3%	-	(5,339)	-9.7%
營業外收入及支出合計	1,118	2.0%	(543)	-1.1%	-	206	0.4%
稅前淨利(損)	1,482	2.6%	(3,714)	-7.4%	-	(5,133)	-9.3%
本期淨利(損)	1,184	2.1%	(4,095)	-8.1%	-	(5,720)	-10.4%
歸屬於母公司業主之本期淨利(損)	1,131	2.0%	(4,104)	-8.1%	-	(5,738)	-10.4%
每股盈餘 ⁽¹⁾⁽²⁾	0.12		(0.45)			(0.60)	
EBITDA ⁽³⁾	8,213	14.4%	4,647	9.2%	76.7%	2,355	4.3%
折舊及攤銷	7,849		7,818			7,694	
資本支出	3,782		4,542			5,656	

附註:

1. 每股盈餘之計算是以本期歸屬於母公司之稅後淨利(損) / 在外流通加權平均普通股股數
2. 截至2024年6月30日，普通股股本為新台幣908億元
3. EBITDA = 營業利益 + 折舊及攤銷
4. 所有數字係由群創光電依據中華民國國際財務報導準則(TIFRS)編制

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